

ABSTRACT OF THE DISCLOSURE

5 A heat-dissipating fin module installed on a heat-generating component of an electronic device for help dissipating heat generated thereby. The heat-dissipating fin module has a heat-conductive substrate in direct contact with the heat-generating component for transferring heat. Through the installation of several first fins and several second fins with curved surfaces and curvature centers on opposite sides, both the heat-conductive area and the heat conducting time are increased. A curved airflow path is formed to provide good convective heat dissipation.